RX64M, RX71M Group

RX Driver Package Ver.1.02

R01AN2606EJ0104
Rev.1.04
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Introduction

This document is the RX64M, RX71M Group RX Driver Package User's Manual, version 1.02.

This User's Manual describes basic structures, features and usage of RX Driver Package applications, and about the sample application program using the FIT modules included in this package.

Target Device

RX64M Group (Renesas Starter Kit+ RX64M)

RX71M Group (Renesas Starter Kit+ RX71M)

When using this application note with your product, careful evaluation is recommended.

And when using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Related Documents

- RX Family Board Support Package Module Using Firmware Integration Technology (R01AN1685EU)
- Firmware Integration Technology User's Manual (R01AN1833EU)
- RX Family Adding Firmware Integration Technology Modules to Projects (R01AN1723EU)
- RX Family Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826EJ)
- The User's Manual provided with the RX Driver Package Application.

Contents

1. Overview

1.1 Applicability

This User's Manual applies to the RX64M, RX71M Group RX Driver Package, version 1.02.

1.2 Operating Environment

This package runs under the operating environment described below.

Table 1-1 Operating Environment (RX64M)

Microcontroller	RX64M Group
Evaluation board	Renesas Starter Kit+ RX64M
Integrated development environment (IDE)	e^2 studio, V3.1.3 or later Or: CS+ V3.00.00 or later
Cross tools	RX Family C/C++ Compiler Package V2.03.00 or later
Emulator	E1, E20

Table 1-2 Operating Environment (RX71M)

Microcontroller	RX71M Group
Evaluation board	Renesas Starter Kit+ RX71M
Integrated development environment (IDE)	e^2 studio, V3.1.3 or later Or: CS+ V3.00.00 or later
Cross tools	RX Family C/C++ Compiler Package V2.03.00 or later
Emulator	E1, E20

2. About RX Driver Package

The RX Driver Package is a software platform (framework) that combines the following modules to be required for development in a single package. Since the package contains multiple modules, you can start developing immediately without having to obtain each module separately.

- Board Support Package (BSP) module
- FIT peripheral function modules (free version)
- FIT middleware modules (free version)
- FIT interface modules

You can develop the user application layer with ease by using the Sample Application Program (RX Driver Package Application) which utilizes the RX Driver Package.

2.1 System Structure

The figure below shows the system structure of the RX Driver Package.

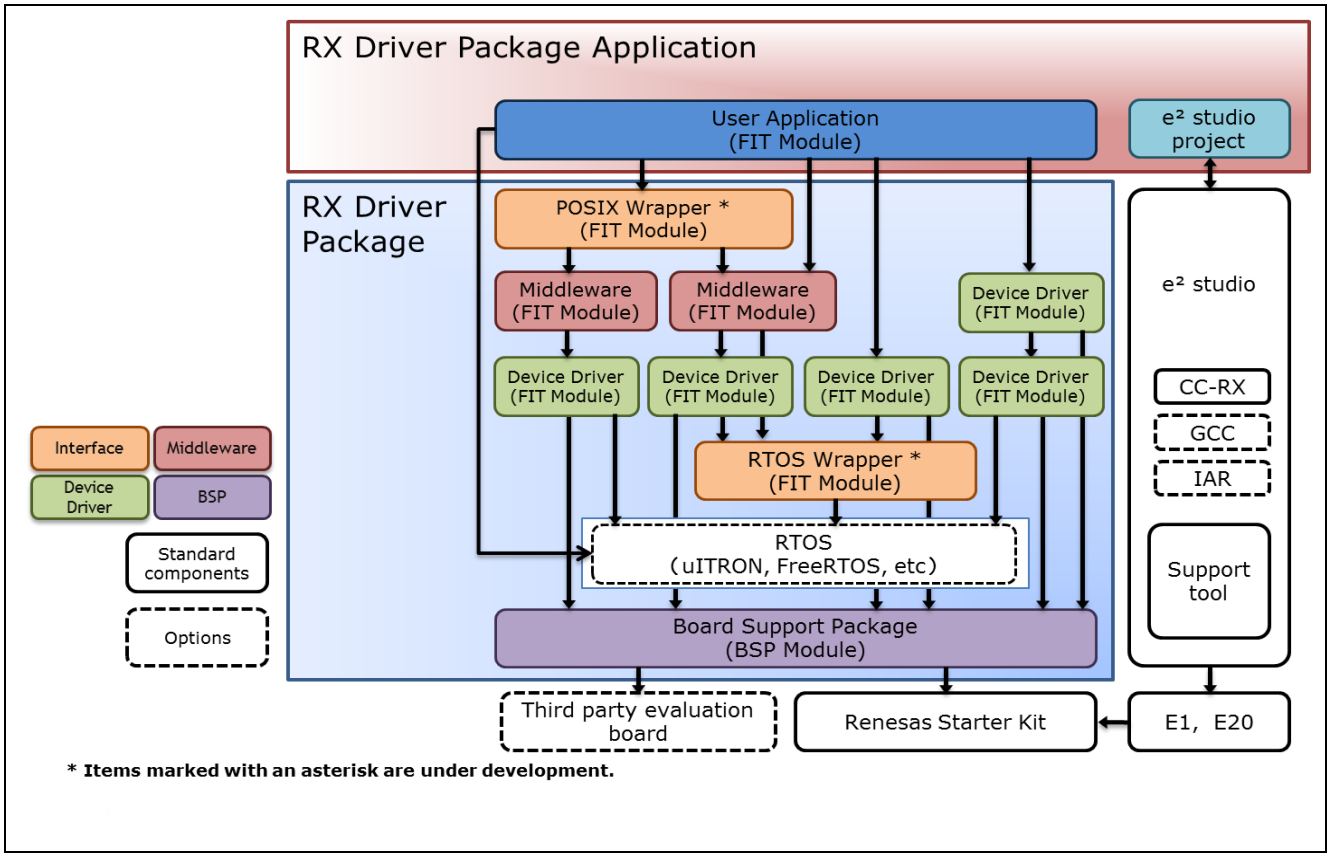


Figure 2-1 System Structure

2.2 RX Driver Package Features

The RX Driver Package has the following features.

(a) Select necessary modules and start developing immediately the application program

You can easily build a system simply by selecting the modules you need from the package. After that, all you have to do is develop the application program.

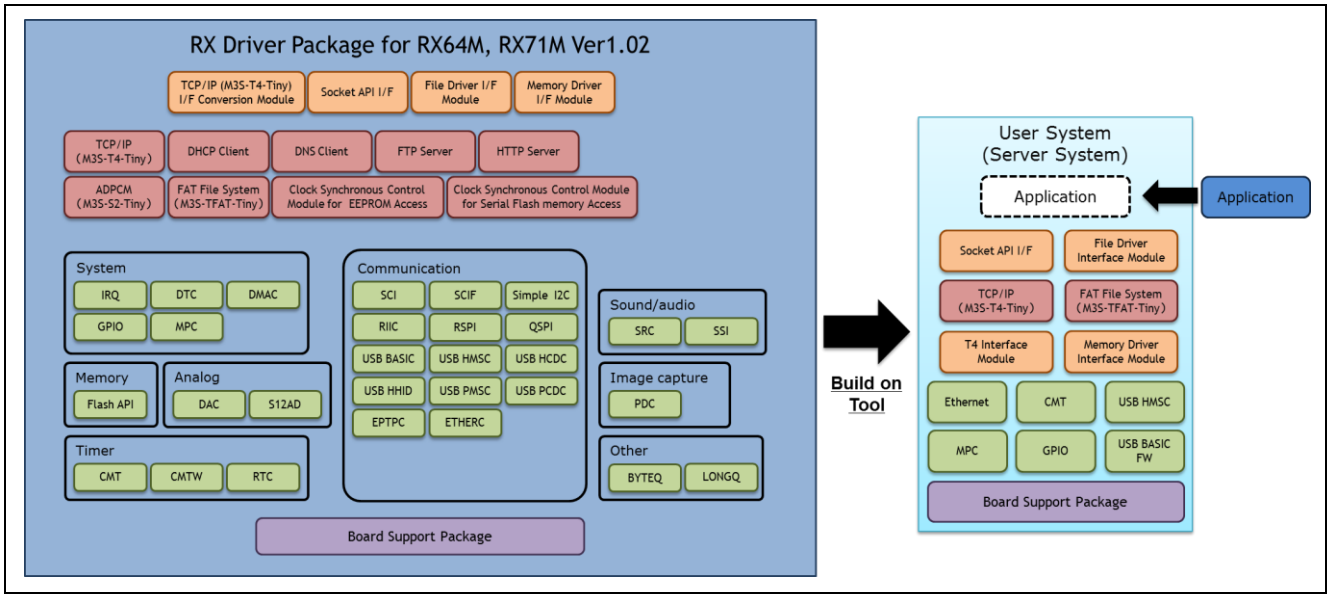


Figure 2-2 An example of system build

(b) Free to use

All the modules included in the RX Driver Package can be used free of charge. Free versions of middleware modules such as TCP/IP and file system are included.

(c) Can upgrade to paid versions of modules

The free versions of modules in the RX Driver Package can be replaced with commercial (paid) versions. By using a commercial (paid) version, all the functionality of the module will be available, as well as support about a commercial version.

(d) Check operation including user application

The RX Driver Package Application is provided as a sample user application that uses the RX Driver Package. The RX Driver Package Application consists of programs for operating each module in the RX Driver Package, and the project files for building the programs. It enables you to start checking the operation of your user application immediately.

3. Structure of the RX64M, RX71M Group RX Driver Package

3.1 Folder Structure

The folder structure used in this package is shown below.

When the ZIP file for this package is downloaded from the Renesas web site and decompressed, a folder of the same name will be present and it will contain a FITModules folder, a reference_documents folder, and this document.

The FITModules folder contains the FIT modules for the modules shown in Table 3-1(as ZIP files and XML files).

The reference_documents folder contains the documentation for using this package in various development

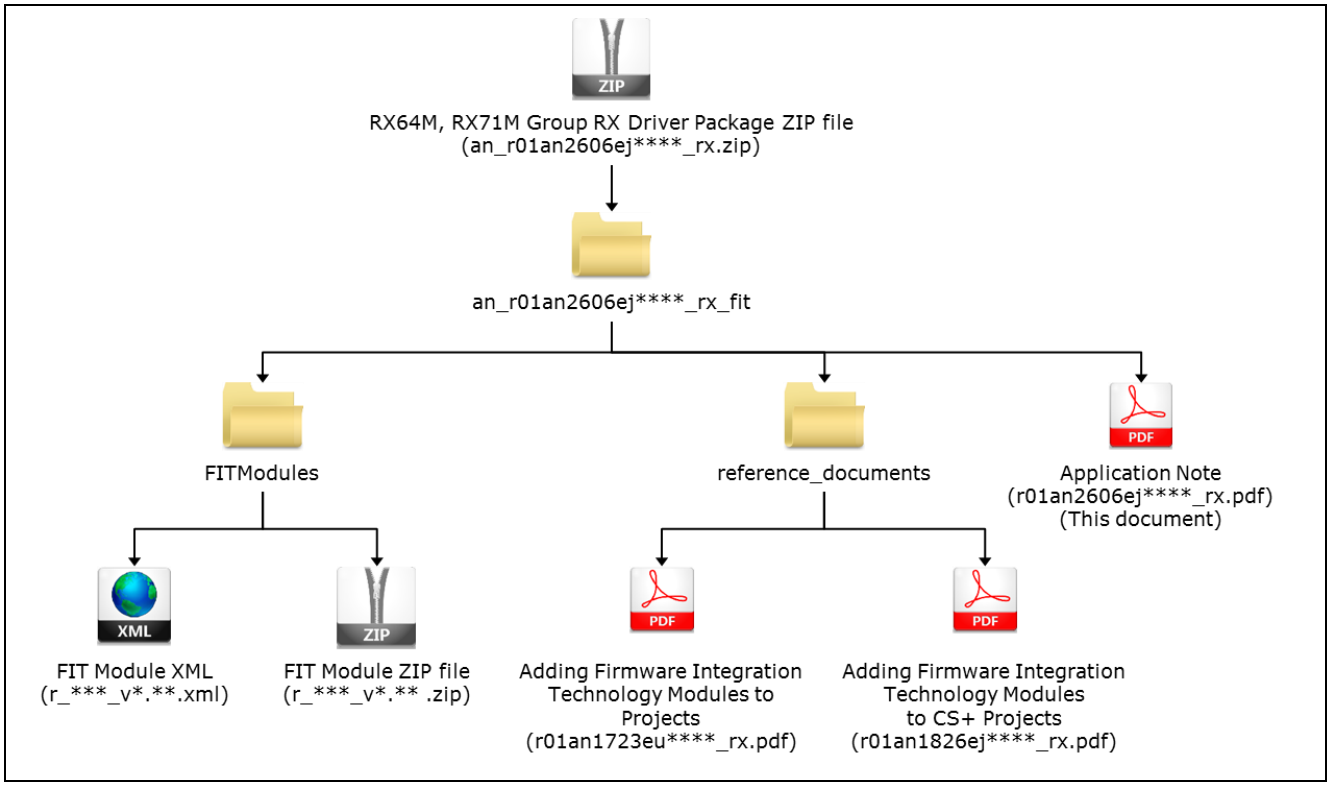


Figure 3-1 Folder Structure of the RX64M, RX71M Group RX Driver Package

3.2 Module Structure

The figure below shows the types and structure of the FIT modules included in this package.

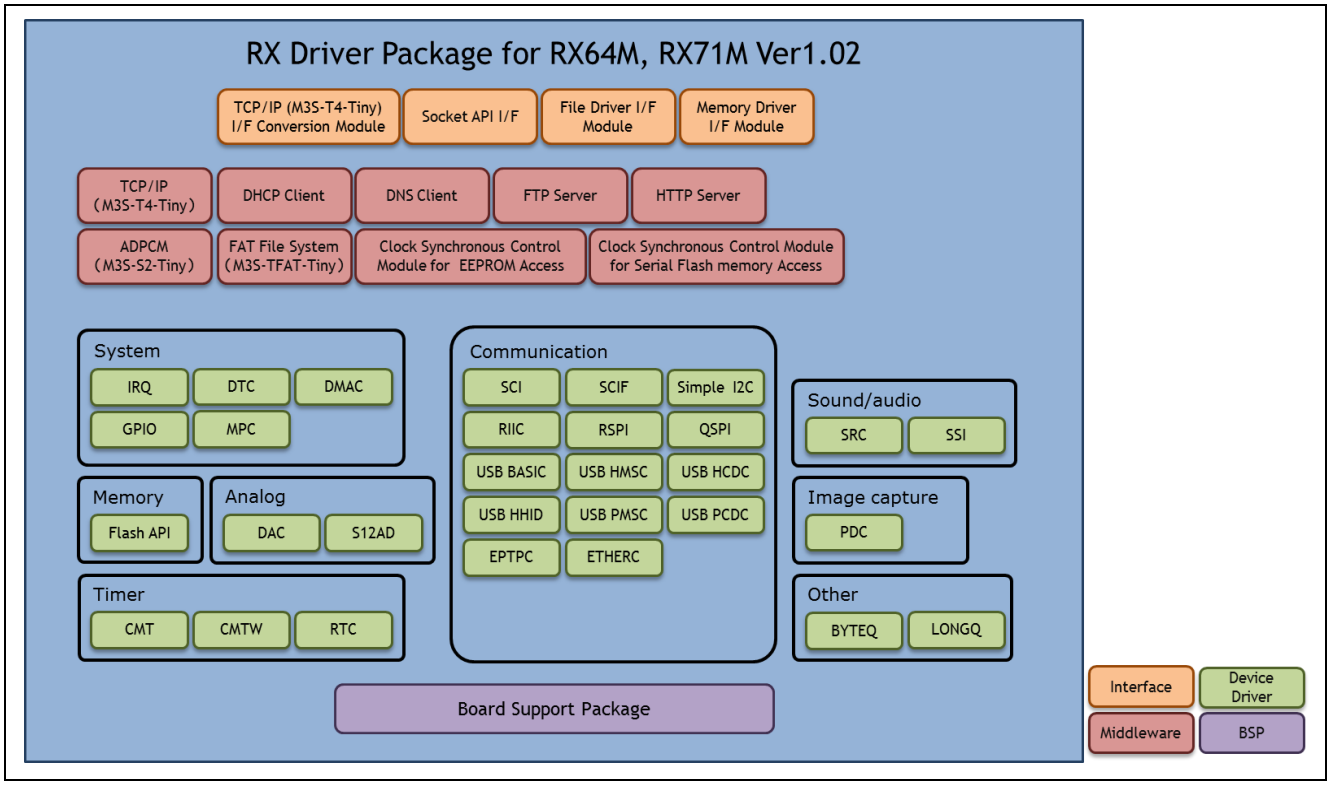


Figure 3-2 RX64M, RX71M Group RX Driver Package FIT Module Structure

3.3 FIT Modules

The table below lists the FIT modules included in this package.

Table 3-1 RX64M, RX71M Group RX Driver Package FIT Modules

Type	Module	FIT Module Name	RX64M	RX71M	Rev.
Board Support Package	Board Support Package (BSP)	r_bsp	✓	✓	3.00
Device Driver	Interrupt Controller (IRQ)	r_irq_rx	✓	✓	1.70
Device Driver	Data Transfer Controller (DTC)	r_dtc_rx	✓	✓	2.03
Device Driver	DMA Controller (DMAC)	r_dmaca_rx	✓	✓	1.03
Device Driver	I/O Ports (GPIO)	r_gpio_rx	✓	✓	1.70
Device Driver	Multi-Function Pin Controller (MPC)	r_mpc_rx	✓	✓	1.70
Device Driver	Compare Match Timer (CMT)	r_cmt_rx	✓	✓	2.60
Device Driver	Compare Match Timer W (CMTW)	r_cmtw_rx	✓	✓	1.10
Device Driver	Real-Time Clock (RTC)	r_rtc_rx	✓	✓	2.30
Device Driver	Serial Communications Interface (SCI: Asynchronous/Clock Synchronous)	r_sci_rx	✓	✓	1.70
Device Driver	Serial Communications Interface with FIFO (SCIF: Asynchronous/Clock Synchronous)	r_scif_rx	✓	✓	1.10
Device Driver	Serial Communications Interface with FIFO (SCIF: Device Driver for Serial Memory Control)	r_scifa_smstr_rx	✓	✓	1.08
Device Driver	Serial Communications Interface (SCI: Simple I^2C Bus)	r_sci_iic_rx	✓	✓	1.70
Device Driver	I^2C Bus Interface (RIIC)	r_riic_rx	✓	✓	1.70
Device Driver	Serial Peripheral Interface	r_rspi_rx	✓	✓	1.30
Device Driver	Serial Peripheral Interface (RSPI: Device Driver for Serial Memory Control)	r_rspi_smstr_rx	✓	✓	1.09
Device Driver	Quad Serial Peripheral Interface (QSPI: Device Driver for Serial Memory Control)	r_qspi_smstr_rx	✓	✓	1.08
Device Driver	USB Basic Firmware	r_usb_basic	✓	✓	1.10
Device Driver	USB Host Mass Storage Class	r_usb_hmsc	✓	✓	1.10
Device Driver	USB Host Communication Device Class	r_usb_hcdc	✓	✓	1.10
Device Driver	USB Host Human Interface Device Class	r_usb_hhid	✓	✓	1.10
Device Driver	USB Peripheral Mass Storage Class	r_usb_pmsc	✓	✓	1.10
Device Driver	USB Peripheral Communications Device Class	r_usb_pcdc	✓	✓	1.10
Device Driver	PTP Module for the Ethernet Controller (EPTPC)	r_ptp_rx	✓	✓	1.11
Device Driver	EPTPC Light Module	r_ptp_light_rx	✓	✓	1.10
Device Driver	Ethernet controller (ETHERC)	r_ether_rx	✓	✓	1.02
Device Driver	Parallel Data Capture Unit (PDC)	r_pdc_rx	✓	✓	1.02
Device Driver	12-Bit A/D Converter (S12AD)	r_s12ad_rx	✓	✓	2.10
Device Driver	D/A Converter (DAC)	r_dac_rx	✓	✓	2.50
Device Driver	Flash Memory (Flash API)	r_flash_rx	✓	✓	1.30
Device Driver	Sampling Rate Converter (SRC)	r_src_api_rx	✓	✓	1.11
Device Driver	Serial Sound Interface (SSI)	r_ssi_api_rx	✓	✓	1.20
Device Driver	Byte Queue Buffer (Data Management)	r_byteq	✓	✓	1.50
Device Driver	Long Queue Buffer (Data Management)	r_longq	✓	✓	1.50

Type	Module	FIT Module Name	RX64M	RX71M	Rev.
Middleware	TCP/IP M3S-T4-Tiny for Embedding	r_t4_rx	✓	✓	2.02
Interface	Interface conversion module for Ethernet Driver and Embedded system M3S-T4-Tiny	r_t4_driver_rx	✓	✓	1.02
Interface	Embedded TCP/IP M3S-T4-Tiny Socket API Module	r_socket_rx	✓	✓	1.22
Middleware	DHCP client using the embedded TCP/IP M3S-T4-Tiny Module	r_t4_dhcp_client_rx	✓	✓	1.03
Middleware	DNS client using the embedded TCP/IP M3S-T4-Tiny Module	r_t4_dns_client_rx	✓	✓	1.02
Middleware	FTP server using the embedded TCP/IP M3S-T4-Tiny Module	r_t4_ftp_server_rx	✓	✓	1.03
Middleware	Web server using the embedded TCP/IP M3S-T4-Tiny Module	r_t4_http_server_rx	✓	✓	1.04
Interface	File driver for FTP server and Web server Module	r_t4_file_driver_rx	✓	✓	1.01
Middleware	Sound playback system and compression system (original ADPCM codec)	r_s2_rx	✓	✓	3.03
Middleware	M3S-TFAT-Tiny (FAT file system)	r_tfat_rx	✓	✓	3.02
Interface	M3S-TFAT-Tiny Memory Driver Interface Module	r_tfat_driver_rx	✓	✓	1.02
Middleware	SPI Serial EEPROM Module	r_eeprom_spi	✓	✓	2.32
Middleware	SPI Serial Flash memory Module	r_flash_spi	✓	✓	2.33

Note: This package includes the M3S-T4-Tiny (TCP/IP protocol stack library) of evaluation version. For the commercial version, please go to the below URL.
http://www.renesas.com/mw/t4

4. Usage Procedures

The RX Driver Package allows programs to be easily constructed by using the FIT plugin included in e^2 studio. The remainder of this section presents a simple usage example using e^2 studio. To use CS+, see the document “RX Family Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826EJ)” included in this package.

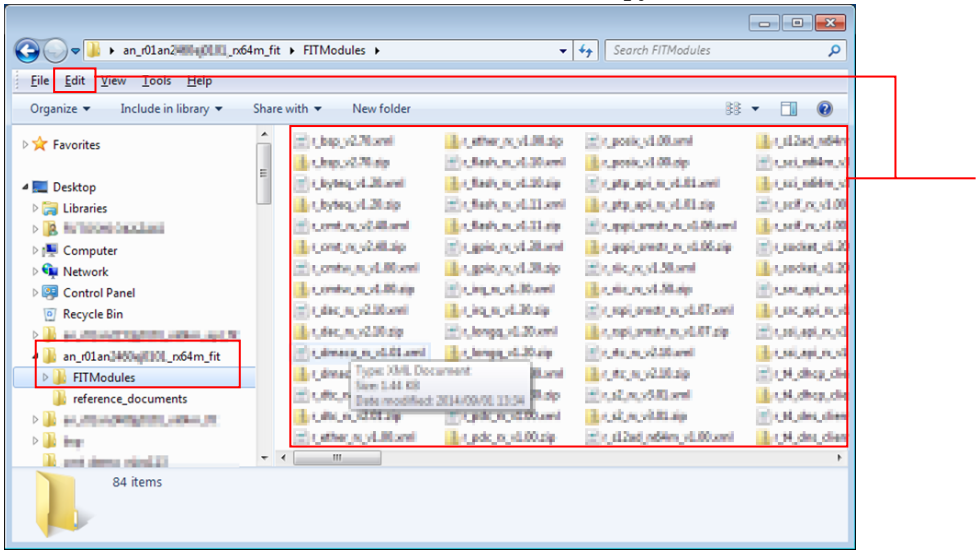
4.1 Environment Used

The RX64M is used as the target microcontroller and the Renesas Starter Kit+ RX64M is used as the target board. If a different environment is used, replace the specifics used in the example with the ones for that environment as you read.

4.2 Install RX Driver Package in e^2 studio

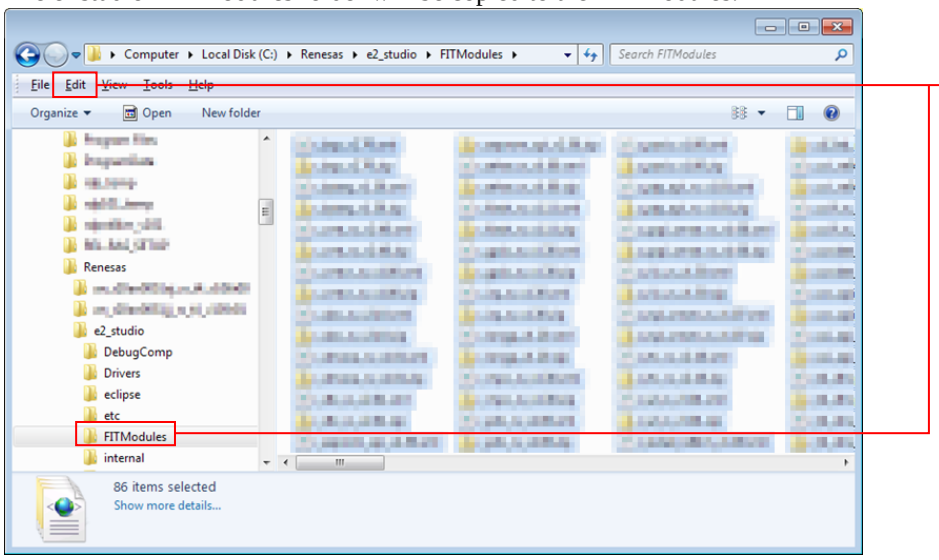
Install the FIT modules in the RX Driver Package into e^2 studio.

1. Decompress the downloaded file **an_r01an2606ej****_rx.zip** into an arbitrary directory.
2. Open the folder that was decompressed and open the **FITModules** folder in that folder.
3. Select all the files in the **FITModules** folder and click **Copy** in the **Edit** menu.



4. Open the e^2 studio install folder (Usually, this will be c:/Renesas/e2_studio.) and open the **FITModules** folder in that folder.

5. Click **Paste** on the **Edit** menu.
   The e^2 studio **FITModules** folder will be copied to the FIT modules.



4.3 Application Creation

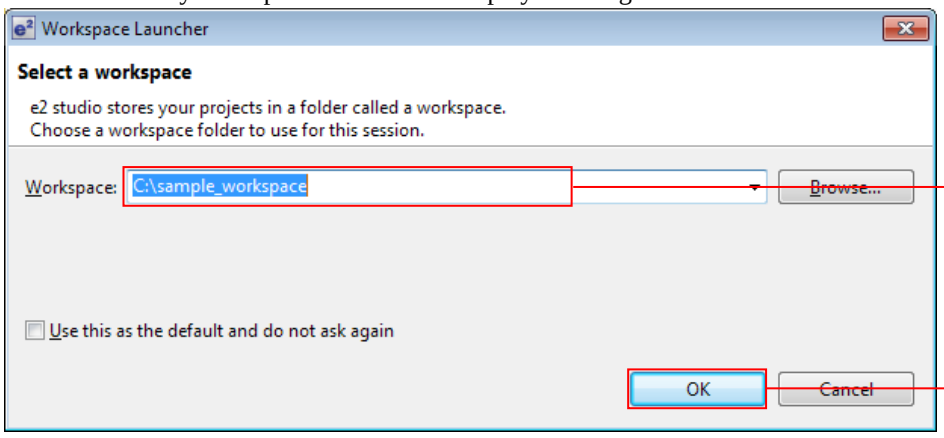
In this section, create a simple application that drives an LED.

4.3.1 Create a Workspace and a Project

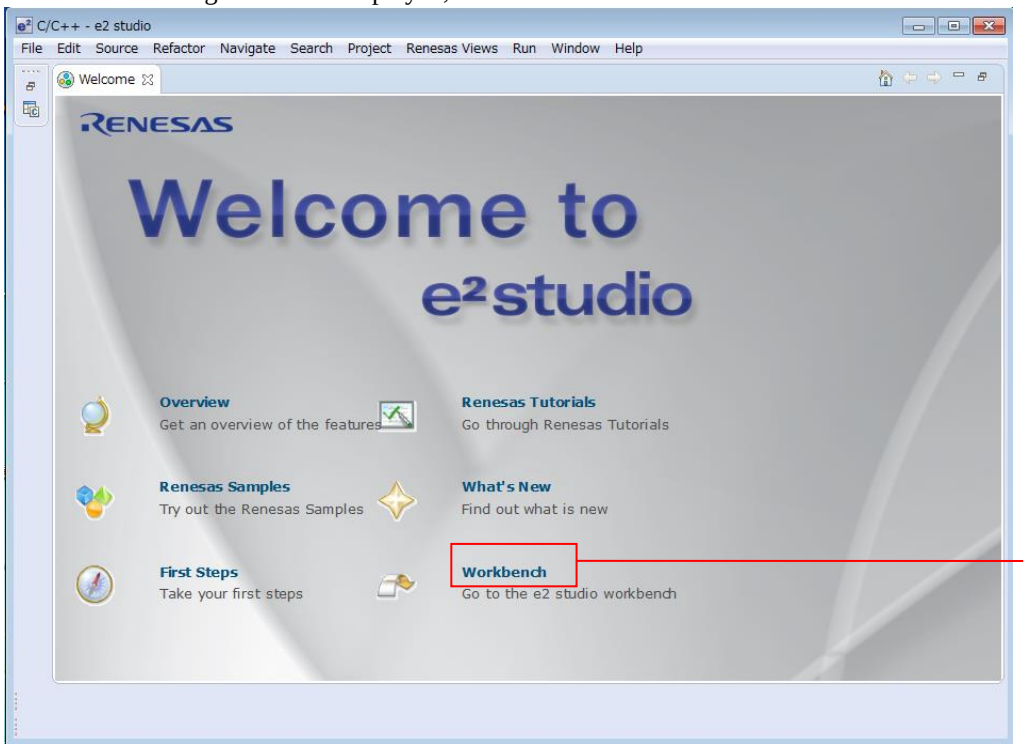
First, create a new workspace and a new project.

1. Start e^2 studio.

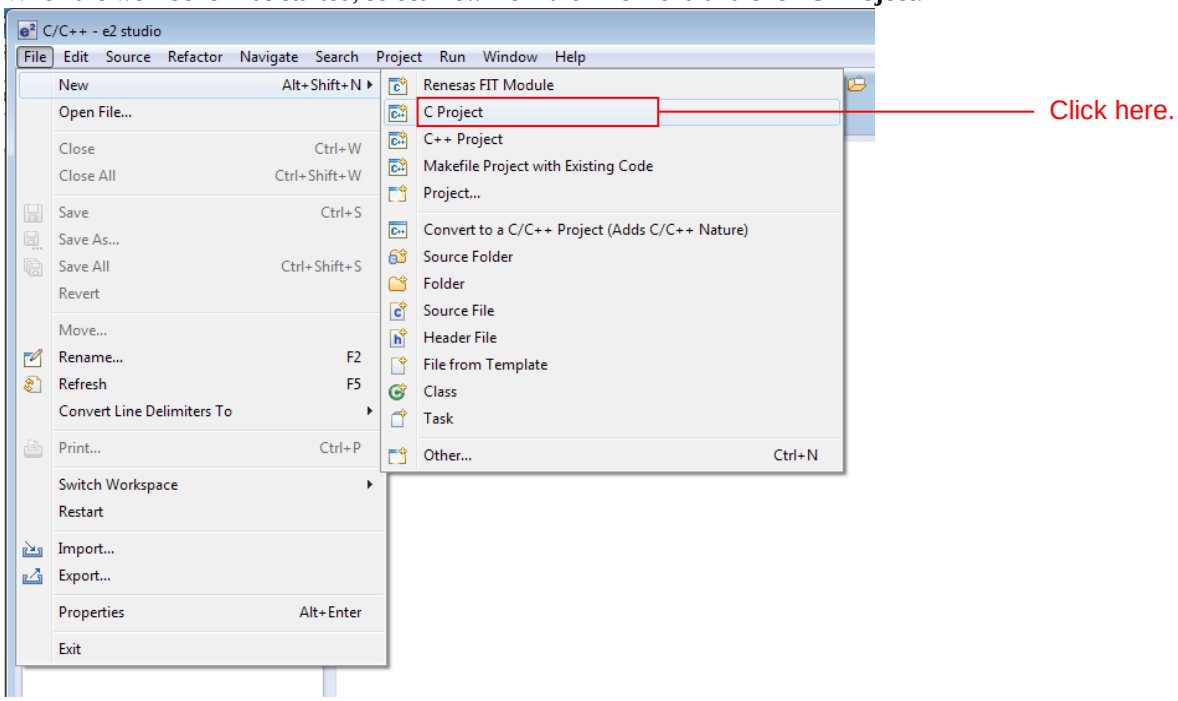
2. Enter an arbitrary workspace folder in the displayed dialog box and click **OK**.



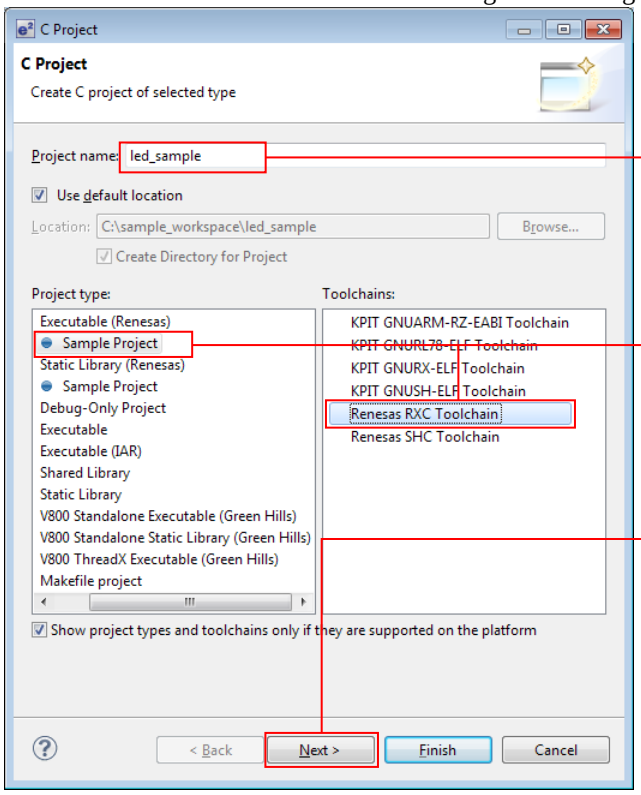
3. When the following window is displayed, click **Workbench**.



4. When the workbench has started, select **New** from the **File** menu and click **C Project**.



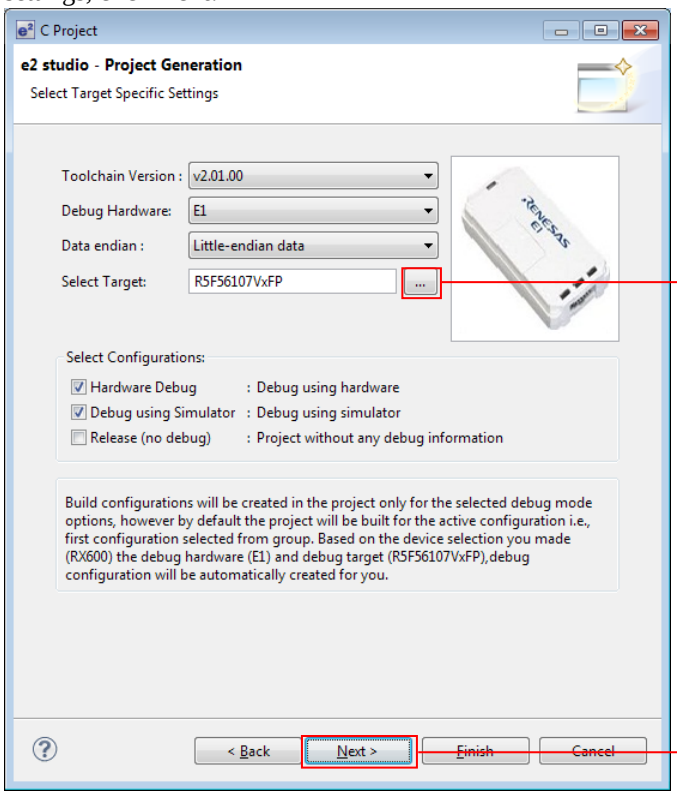
5. Enter the project name. For the project type, click **Sample Project** under **Executable (Renesas)**. For the tool chain, click **Renesas RXC Toolchain**. After making these settings, click **Next**.



Enter the project name.

Click here.

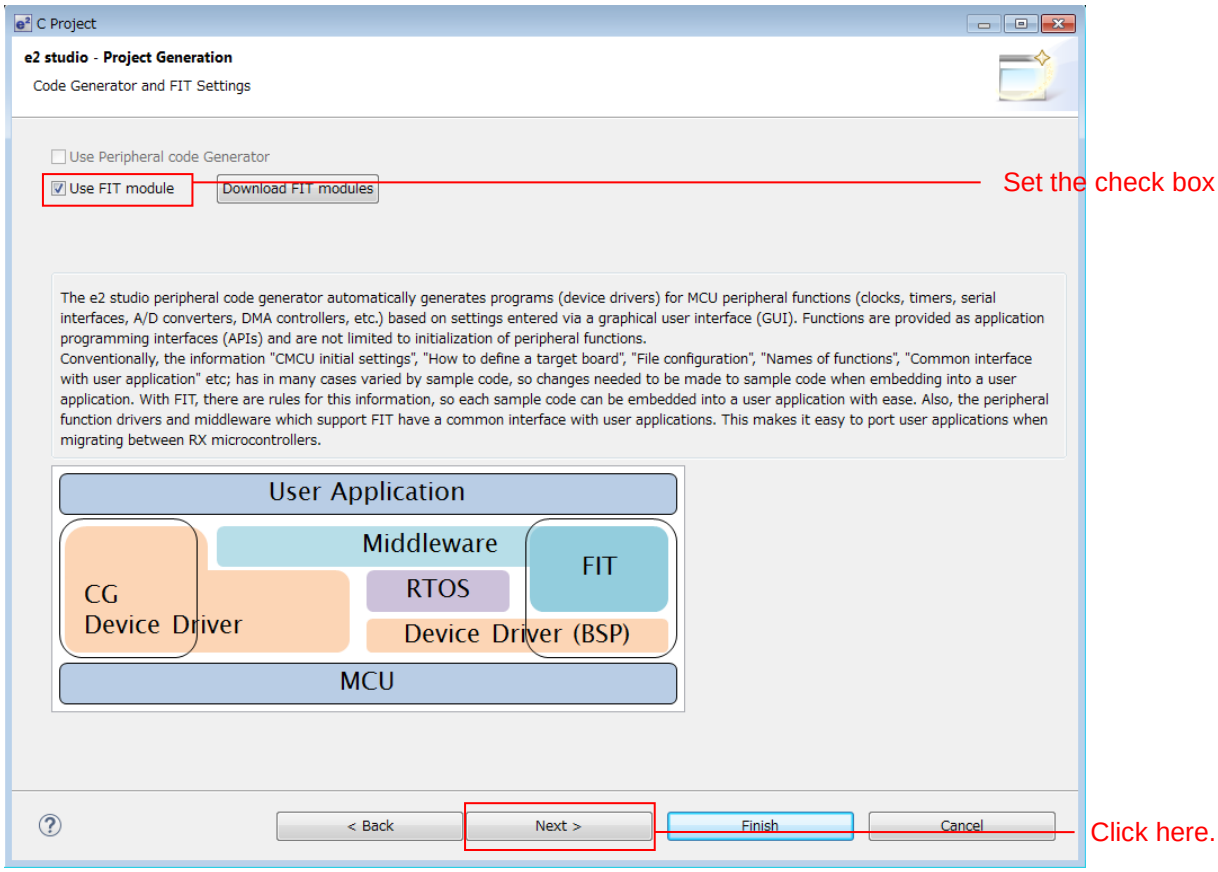
6. Select the target. Click the "..." button under **Target Selection** and select **R5F564MLCxFC**. After making these settings, click **Next**.



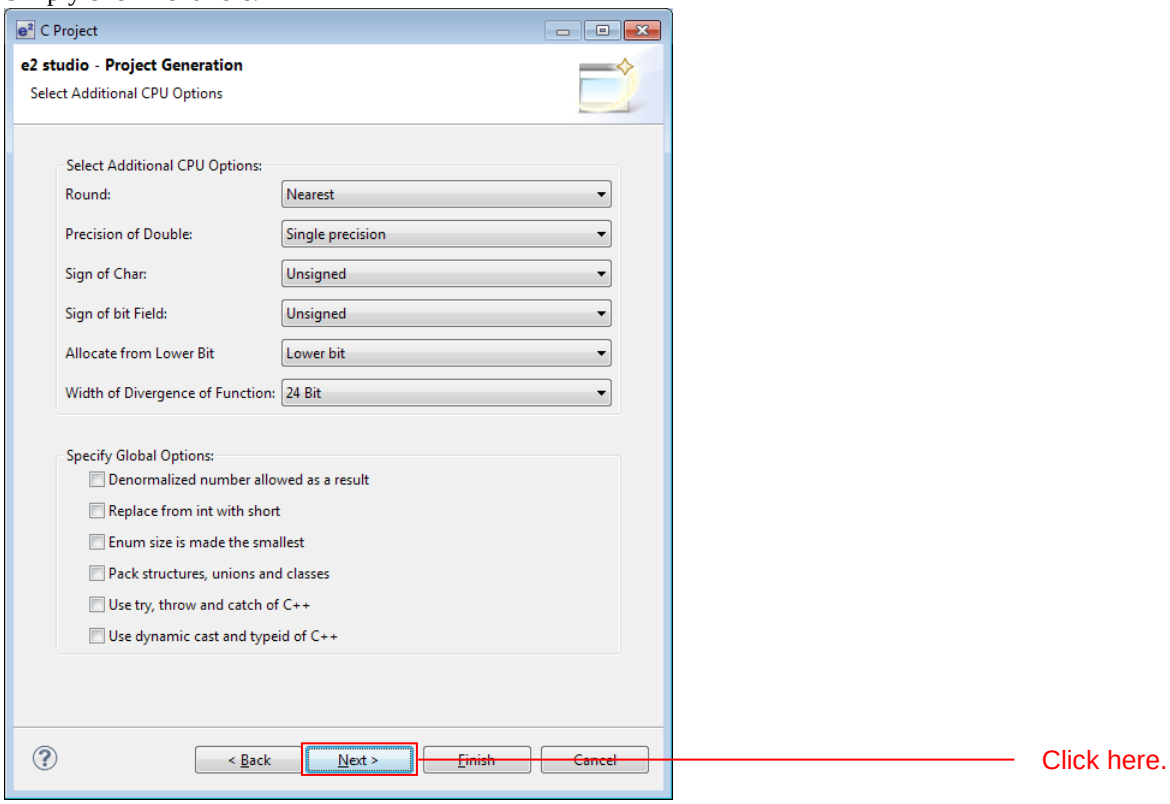
Click here and select **R5F564MLCxFC**.

Click here.

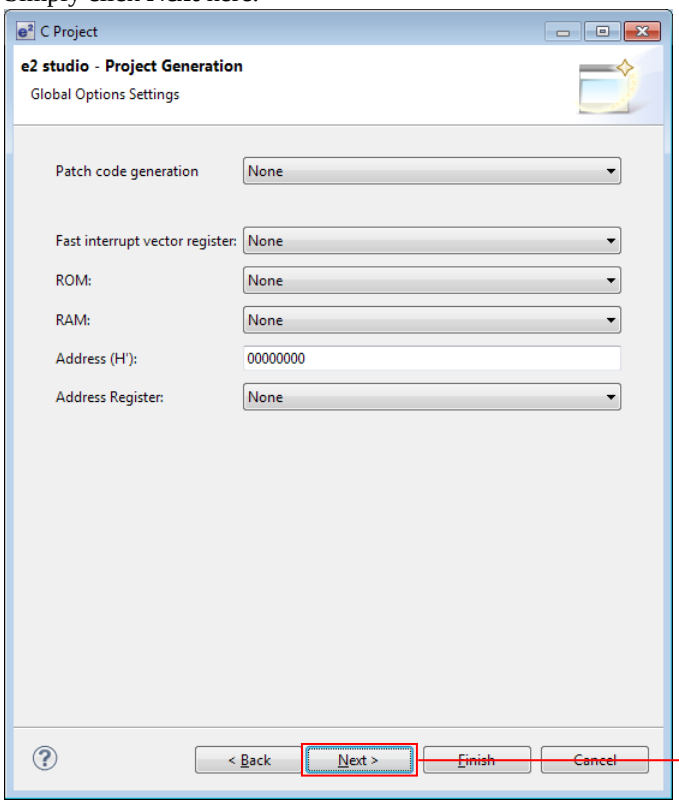
7. Set the check box of “Use FIT module” and click **Next** here.



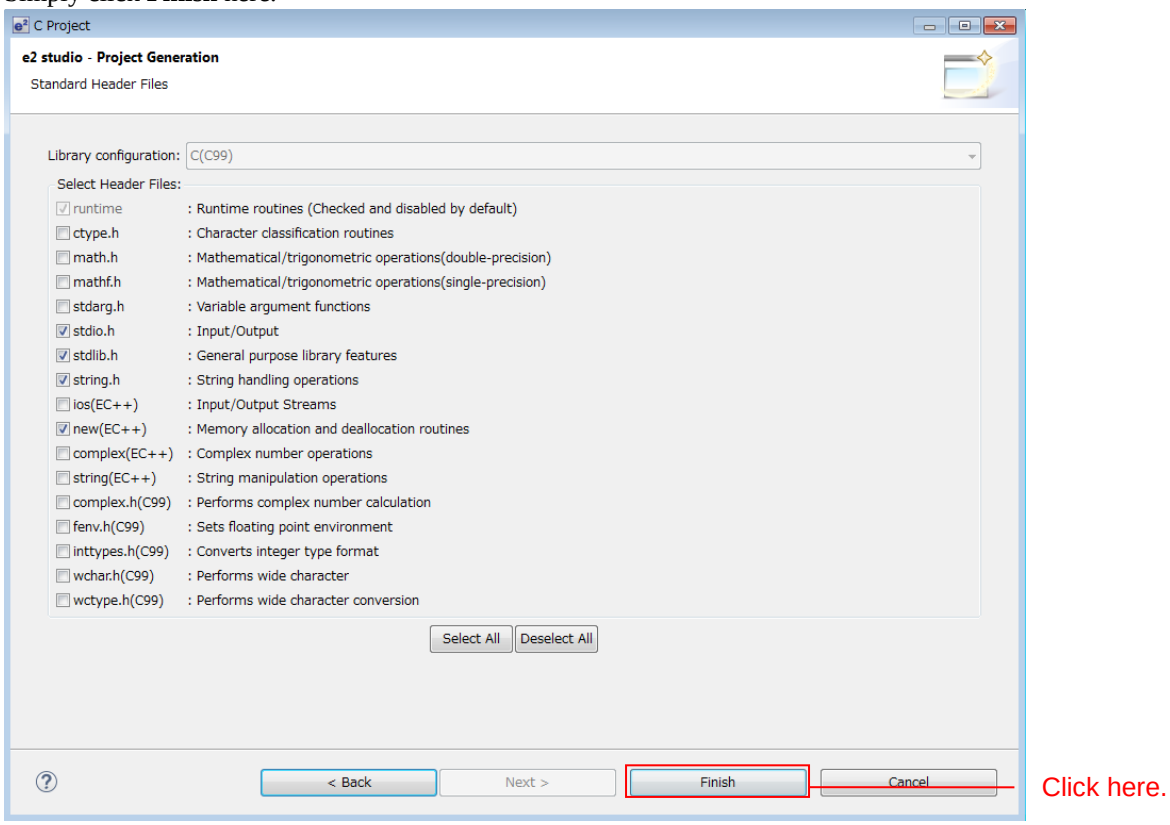
8. Simply click **Next** here.



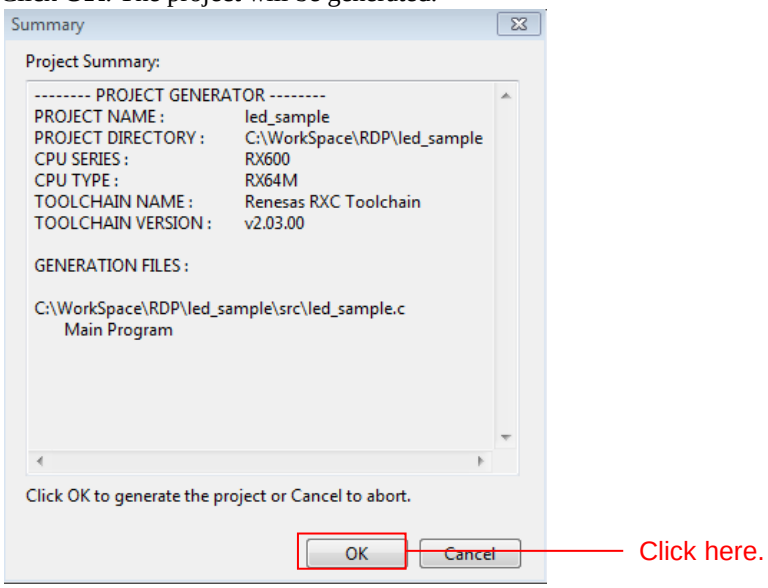
9. Simply click **Next** here.



10. Simply click **Finish** here.



11.Click **OK**. The project will be generated.

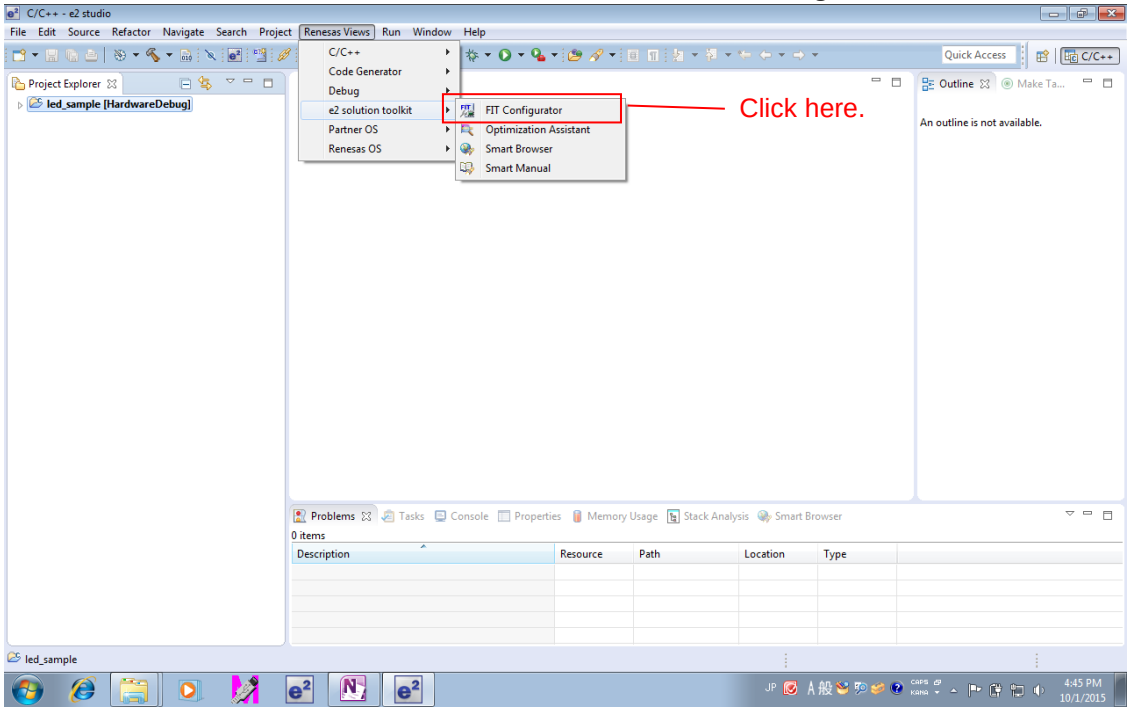


4.3.2 Install the FIT Modules with the FIT Plugin.

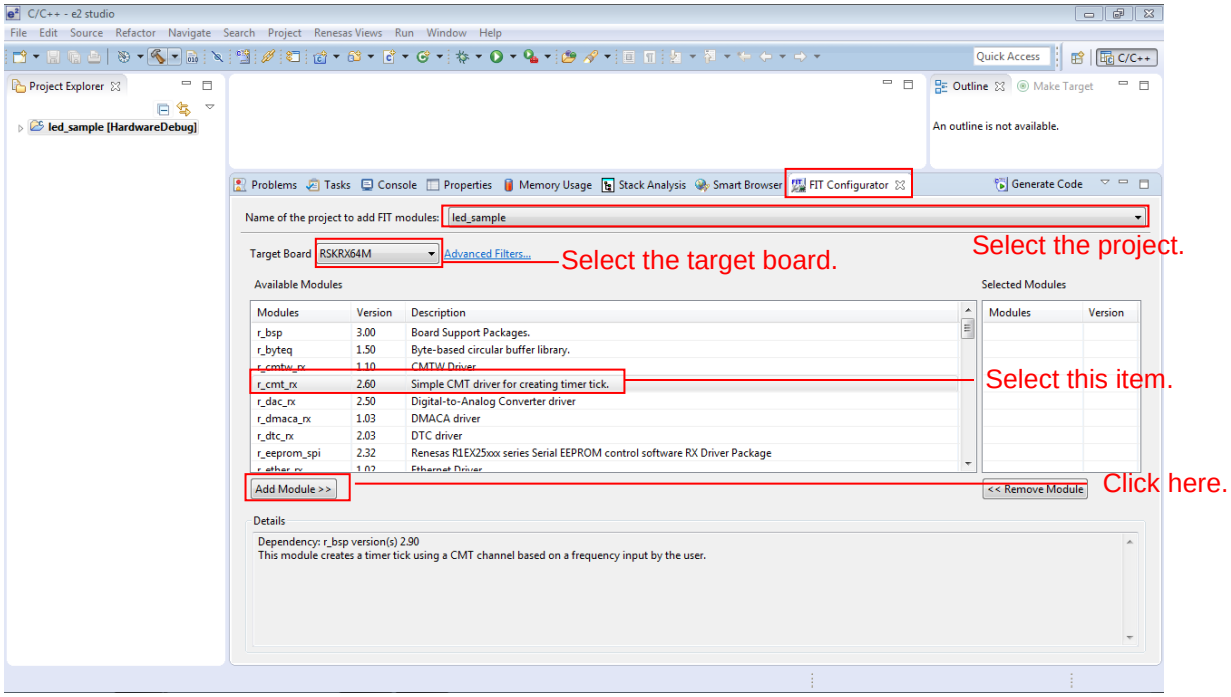
Install the required modules with the FIT plugin into the created project.

Here, install the BSP module (r_bsp) and the compare match timer driver (r_cmt_rx).

1. In the **Renesas Views** menu, select **e2 solution toolkit** and click **FIT Configurator**.

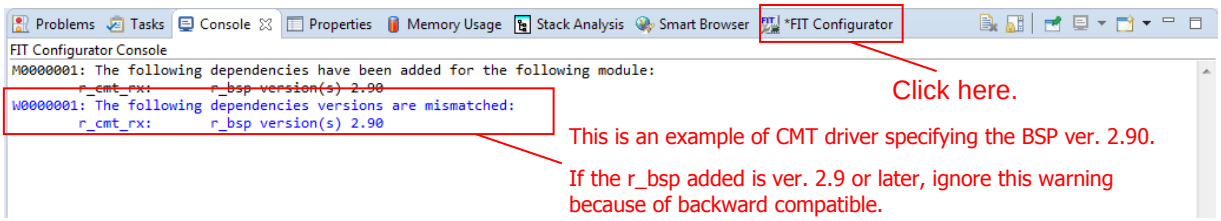


2. In the **FIT Configurator** tab,
   Select the created project with **Project to Add FIT Module** to.
   Next, select **RX64M** under **Group** and select **RSKRX64M** from **Target Board**.
   Next, click **r_cmt_rx** in the module list and click **Add Module** >>.

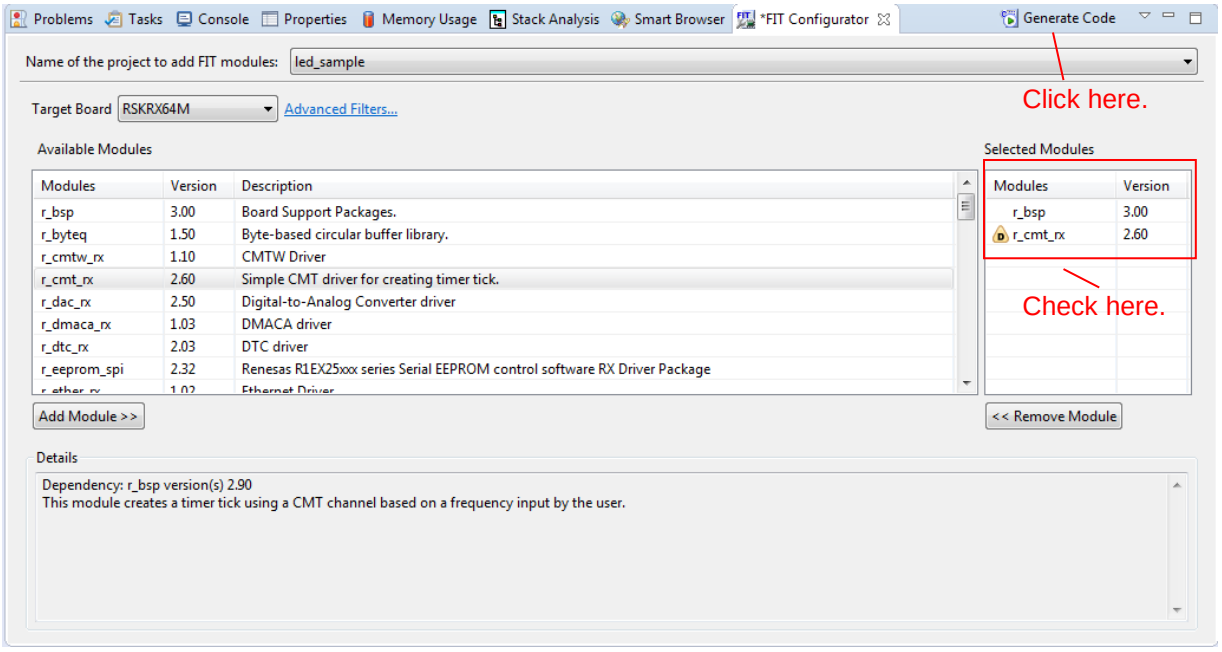


3. In the **Console** tab,
   The **r_bsp** having a dependency with **r_cmt_rx** is also added at a time. Note*
   Click **FIT Configurator** again.

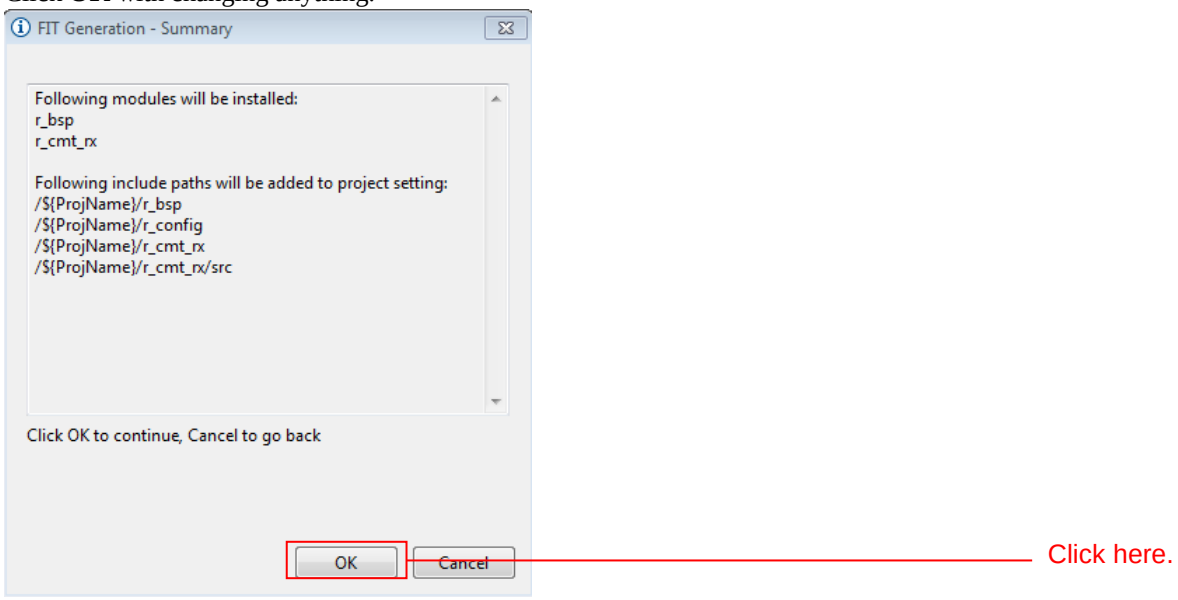
   Note*: Additional FIT driver specifies the adaptable "r_bsp" version.
   If the "r_bsp" versions specified and added mismatch according to the time of FIT driver release, Warning (W0000001) is output on the console screen.
   If the "r_bsp" version added is the one specified or later, Warning can be ignored, as the new "r_bsp" version is backward compatible.



4. Check **r_bsp** and **r_cmt_rx** are added in **Selected Modules**. The mark on **r_cmt_rx** indicates occurrence of the Warning explained in the above 3.
   Then, click **Generate Code**.



5. Click **OK** with changing anything.



4.3.3 Create an LED Driving Program

Create a program that toggles the LED0 on/off state every 0.5 seconds using the compare match timer.

Open the file src/(the project name).c and modify it as shown below.

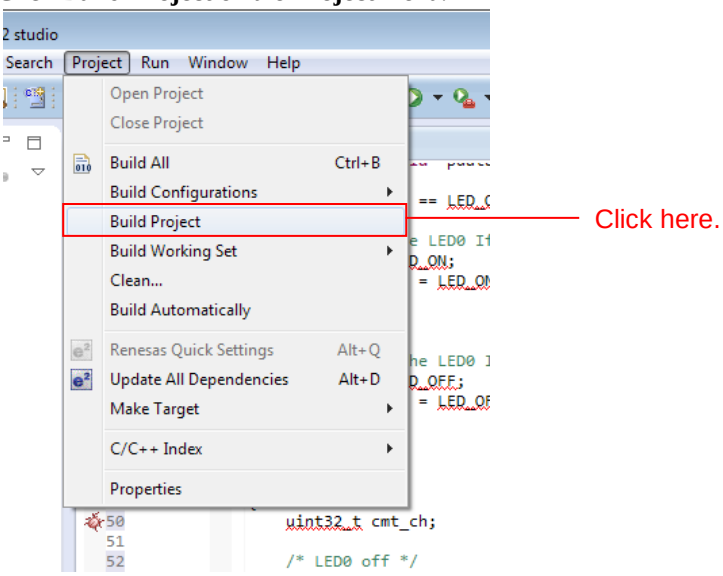
src/(the project name).c

```
#include "platform.h"
#include "r_cmt_rx_if.h"

/* LED Currently status */
uint32_t ledstatus = LED_OFF;

void call_back(void *pdata)
{
 if (ledstatus == LED_OFF)
 {
    /* Turn ON the LED0 If the status is LED_OFF */
  LED0 = LED_ON;
  ledstatus = LED_ON;
 }
 else
 {
    /* Turn OFF the LED0 If the status is LED_ON */
  LED0 = LED_OFF;
  ledstatus = LED_OFF;
 }
}

void main(void)
{
 uint32_t cmt_ch;

 /* LED0 off */
 LED0 =LED_OFF;
 /* Create of 0.5 second(2Hz) cyclic timer. */
 R_CMT_CreatePeriodic(2, &call_back, &cmt_ch);

 while(1);
}
```

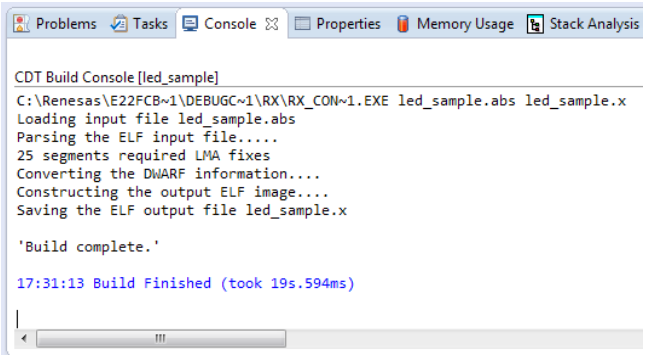
4.3.4 Build and Try Running the Program

Build the program just created and verify that it runs.

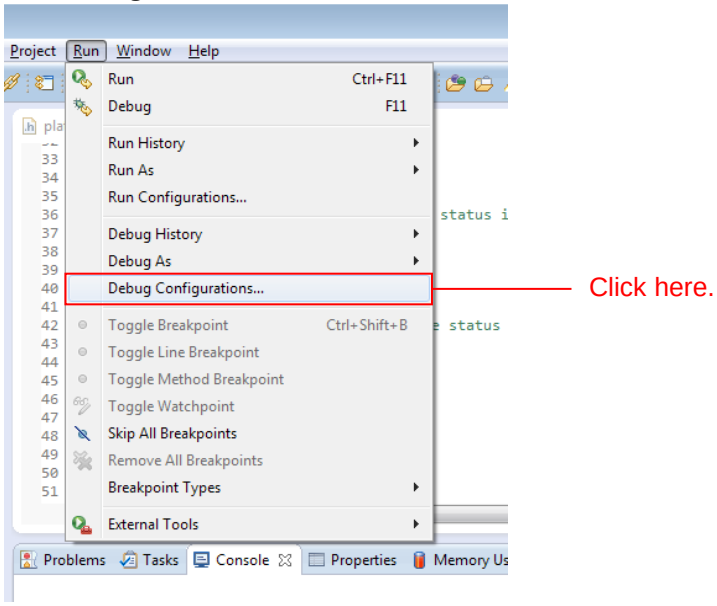
1. Click **Build Project** on the **Project** menu.



2. When the build completes, the following will be displayed in **Console** view.

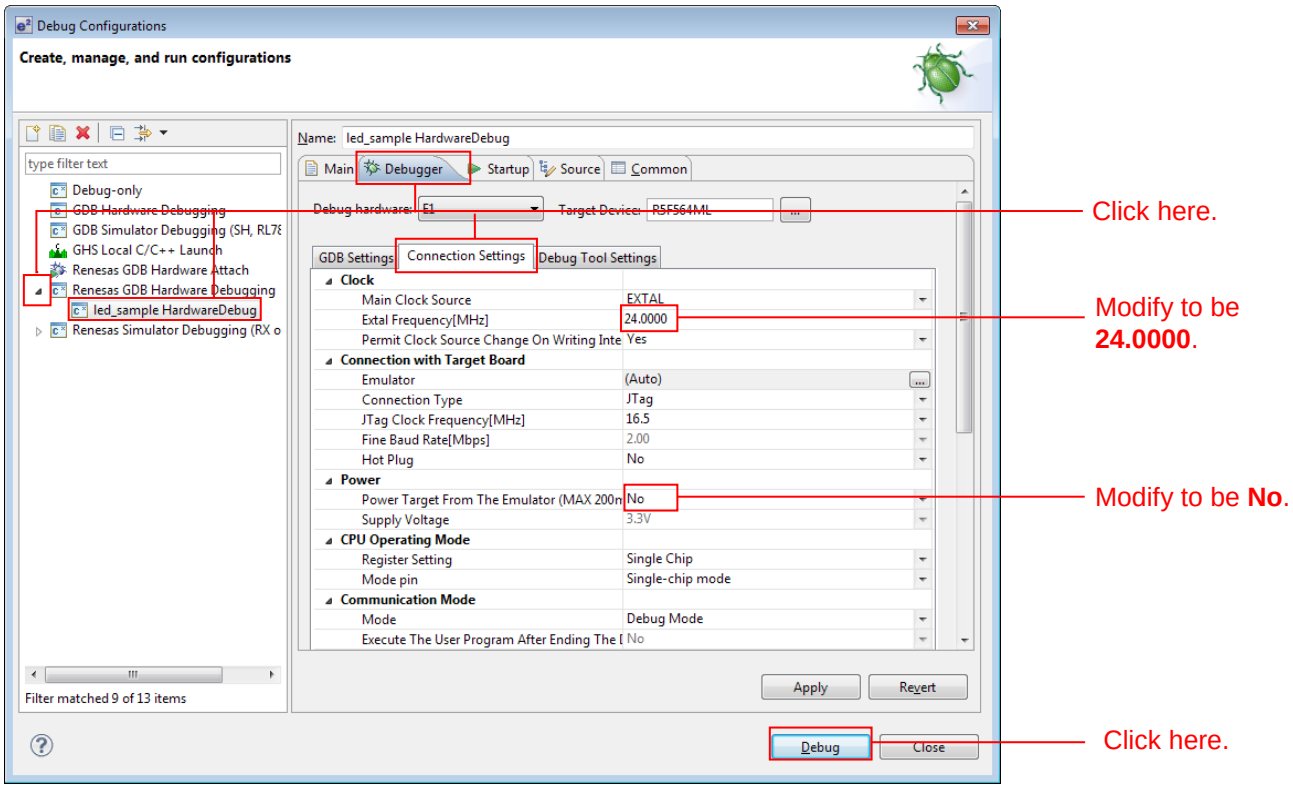


3. Click **Debug Build** on the **Run** menu.

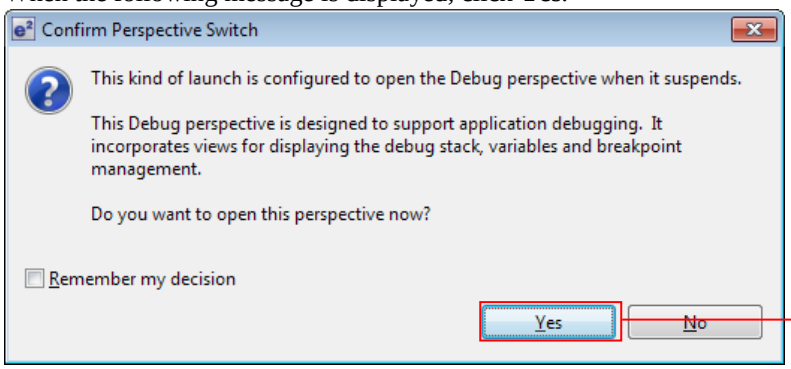


4. Click ◢ under the **Renesas GDB Hardware Debugging and c**lick **led_sample HardwareDebug**. Click the **Debugger** tab and click **Connection Setting**.
   Modify **EXTAL Frequency** to be **24.0000** and change **Provide Power from Emulator** to **No ***.
   When these changes have been made, click **Debug**.

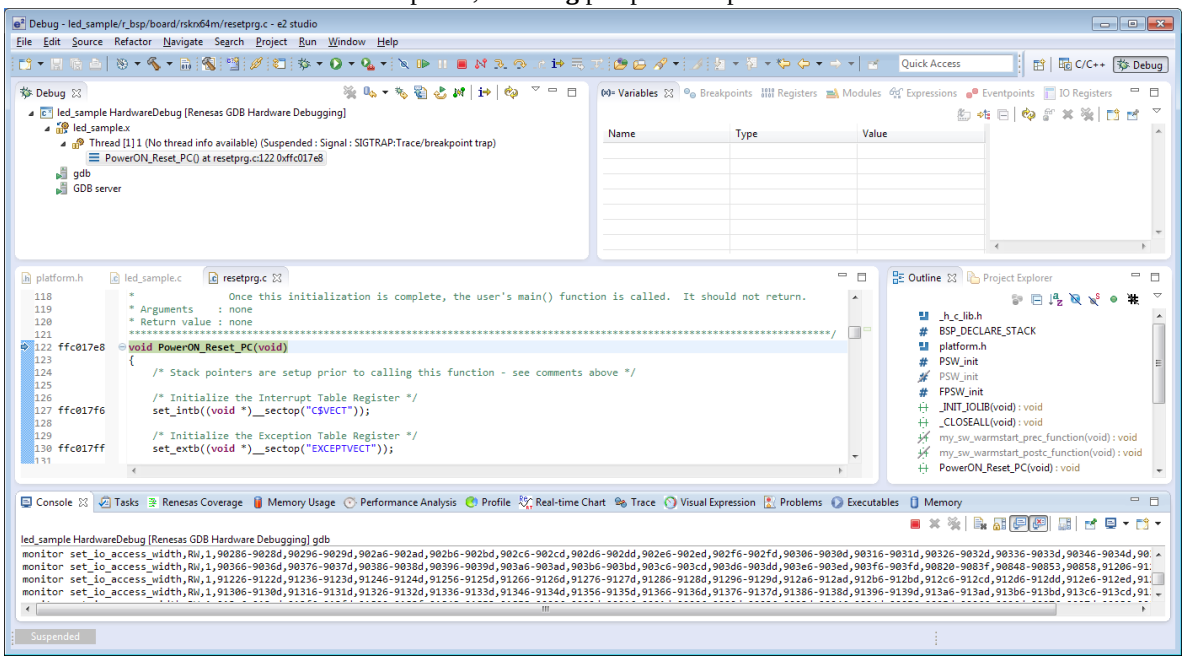
   Note : This is setting when using an external power supply. When supplying power from the emulator, select **Yes.**



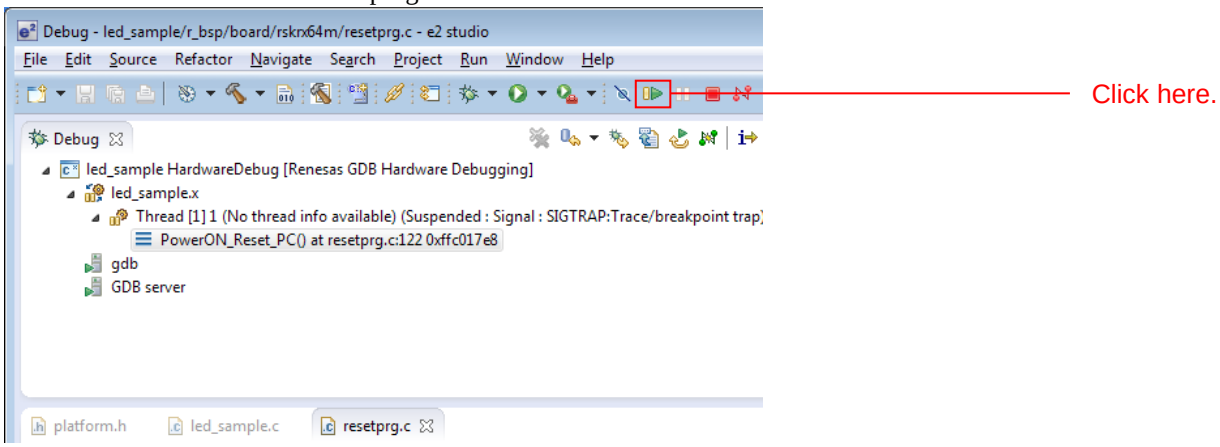
5. When the following message is displayed, click **Yes**.



6. When the load module download completes, a **Debug** perspective opens.



7. Click **Restart** on the toolbar. The program will be executed and a break will occur at the start of the main function.



8. After the break at the start of the main function, click **Restart** on the tool bar again.
The project will be run and the program will iterate toggling LED0 with a period of 0.5 seconds.

5. RX Driver Package Application

5.1 RX Driver Package Application Structure

The RX Driver Package Application is a sample application program provided so that users can use the RX Driver Package easily. The RX Driver Package Application consists of an application program that operates using device drivers and middleware included in the RX Driver Package and a project file for building that application. This allows users to start evaluation quickly.

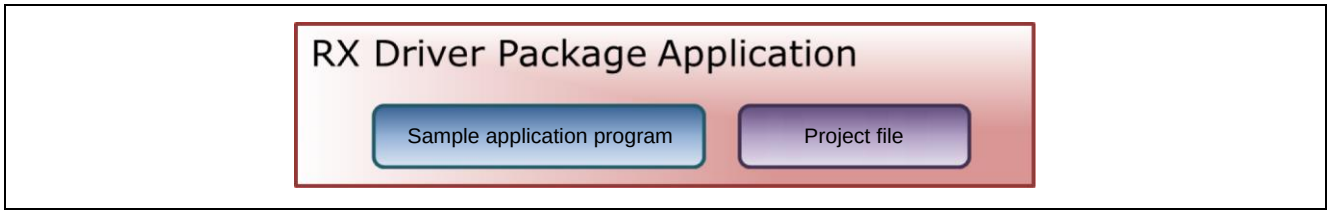


Figure 5-1 RX Driver Package Application Structure

Renesas plans to release a variety of types of this RX Driver Package Application in the future, such as system programs that operate using a combination of multiple drivers and middleware and evaluation programs for independent modules from the RX Driver Package.

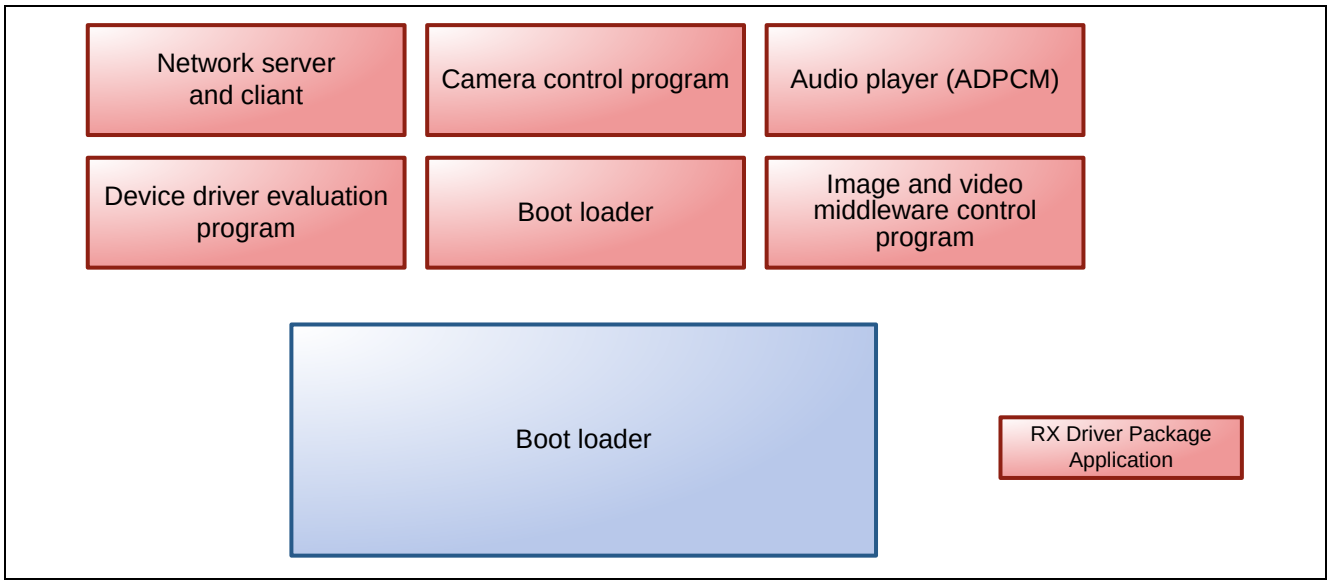


Figure 5-2 Types of RX Driver Package Application

6. Supplement

6.1 M3S-T4-Tiny (TCP/IP protocol stack)

This package include the M3S-T4-Tiny (TCP/IP protocol stack library) of evaluation version. For the commercial version, please go to the below URL.

http://www.renesas.com/mw/t4

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Revision History

		Description	
Rev.	**Date**	**Page**	**Summary**
1.00	Sep 1, 2014	-	First edition issued
1.01	Jan 5, 2015	-	Updated existing modules to latest modules. Added new release modules to the package.
1.03	Feb 29, 2016	-	Updated existing modules to latest modules. Added RX71M. Updated e2studio version and changed set-up procedure.
		8	In Table 3-1 RX64M, RX71M Group RX Driver Package FIT Modules in 3.3 FIT Modules, Changed Rev. of GPIO, MPC, RTC, Serial Peripheral Interface and Flash API. Change "PTP controller for Ethernet controller (EPTPC)" to "EPTPC Light Module".
		9	In Table 3-1 RX64M, RX71M Group RX Driver Package FIT Modules in 3.3 FIT Modules, Change "r_socket" to "r_socket_rx ".
		-	Removed the PTP controller for Ethernet controller (EPTPC) module. Added the EPTPC Light module.
1.04	May.16, 2016	4	2.1 System Structure Changed 'POSIX Wrapper' to 'POSIX Wrapper *'. Added '*' item in Figure 2-1.
		5	2.2 RX Driver Package Features Removed 'POSIX API I/F' in Figure 2-2.
		6	3.1 Folder Structure Removed 'POSIX API I/F' in Figure 3-1.
		7	3.2 Module Structure Removed 'POSIX API I/F' in Figure 3-1.
		8	3.3 FIT Modules Added the PTP controller for Ethernet controller (EPTPC) module. Updated the EPTPC Light module. Removed the POSIX Wrapper module.
		18	4.3.2 Install the FIT Modules with the FIT Plugin 3. In the Console tab, Changed the description for r_bsp.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins
   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.
   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.
2. Processing at Power-on
   The state of the product is undefined at the moment when power is supplied.
   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.
3. Prohibition of Access to Reserved Addresses
   Access to reserved addresses is prohibited.
   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.
4. Clock Signals
   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.
   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.
5. Differences between Products
   Before changing from one product to another, i.e. to a product with a different type number, confirm that the change will not lead to problems.
   — The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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